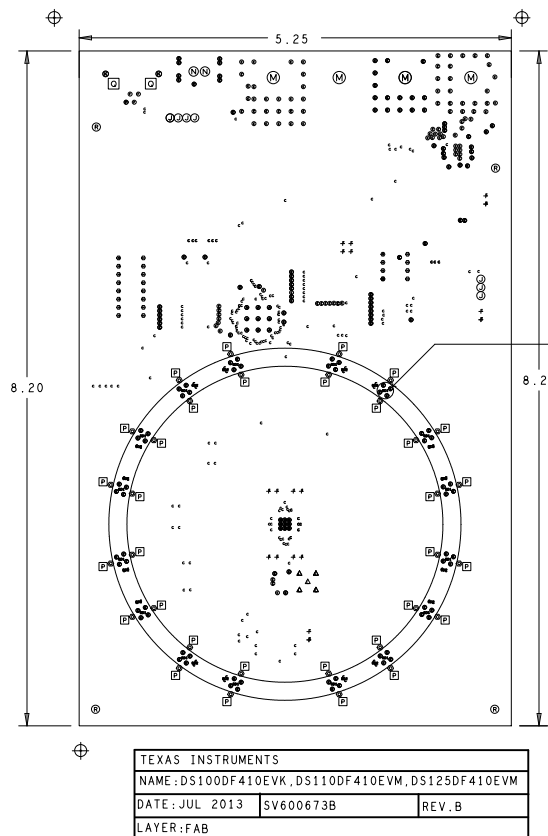


LAYER STACK-UP THIS IS A 8 LAYER BOARD

| | | | | |
|---------|-------------------------|-----------|---------|----------------------------|
| LAYER 1 | TOP SIDE SOLDER MASK | .80 MILS | | |
| LAYER 2 | R04350B | 10.0 MILS | TOP | (COPPER+PLATING=2.30 MILS) |
| LAYER 3 | PLC-370HR | 3.80 MILS | GND-1 | .60 MILS |
| LAYER 4 | PLC-370HR | 10.0 MILS | SIG-1 | .60 MILS |
| LAYER 5 | PLC-370HR | 6.24 MILS | GND-2 | .60 MILS |
| LAYER 6 | PLC-370HR | 10.0 MILS | POWER-1 | .60 MILS |
| LAYER 7 | PLC-370HR | 4.04 MILS | POWER-2 | .60 MILS |
| LAYER 8 | PLC-370HR | 10.0 MILS | GND-3 | .60 MILS |
| | BOTTOM SIDE SOLDER MASK | .80 MILS | BOTTOM | (COPPER+PLATING=2.30 MILS) |

| DRILL CHART: TOP to BOTTOM | | | | |
|----------------------------|-------|-----------|------------|-----|
| ALL UNITS ARE IN MILS | | | | |
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| * | 10.0 | +3.0/-3.0 | PLATED | 208 |
| * | 10.0 | +3.0/-3.0 | PLATED | 9 |
| * | 10.0 | +3.0/-3.0 | PLATED | 9 |
| - | 10.01 | +3.0/-3.0 | PLATED | 16 |
| - | 13.0 | +3.0/-3.0 | PLATED | 16 |
| * | 15.0 | +3.0/-3.0 | PLATED | 231 |
| * | 36.0 | +3.0/-3.0 | PLATED | 4 |
| * | 36.0 | +4.0/-1.0 | PLATED | 2 |
| * | 36.0 | +4.0/-1.0 | PLATED | 22 |
| ⊙ | 40.0 | +3.0/-3.0 | PLATED | 7 |
| * | 40.0 | +3.0/-3.0 | PLATED | 162 |
| ⊙ | 62.0 | +3.0/-3.0 | PLATED | 2 |
| △ | 70.0 | +3.0/-3.0 | PLATED | 5 |
| Ⓜ | 152.0 | +3.0/-3.0 | PLATED | 4 |
| Ⓜ | 35.43 | +2.0/-2.0 | NON-PLATED | 2 |
| ⊙ | 63.0 | +2.0/-2.0 | NON-PLATED | 32 |
| Ⓜ | 108.0 | +2.0/-2.0 | NON-PLATED | 32 |
| Ⓜ | 128.0 | +5.0/-5.0 | NON-PLATED | 2 |
| ⊙ | 250.0 | +2.0/-2.0 | NON-PLATED | 4 |



| BACKDRILL: BOTTOM to GND-2 | | | | |
|----------------------------|-------|-----------|--------|-----|
| ALL UNITS ARE IN MILS | | | | |
| FIGURE | SIZE | TOLERANCE | PLATED | QTY |
| - | 10.01 | +3.0/-3.0 | PLATED | 16 |
| - | 13.0 | +3.0/-3.0 | PLATED | 16 |

NOTES:

- DRILL SIZES LISTED IN LEGEND ARE CONSIDERED FINISHED.
- VENDOR IS REQUIRED TO SELECT TOOLING FOR OVERDRILLING.
- LEGEND DOES NOT SPECIFY DEPTH INTO ADJACENT DIELECTRIC LAYER.
- SHOULD NOT BREAK THE SIGNAL PAD IN LAYER 3(SIGNAL1)

DETAIL A (NO OF LOCATION=16x5=75)

- * ALL THE DRILLS INSIDE THIS AREA NEEDS TO BE CONDUCTIVE FILLED FROM TOP SIDE.
- * SMOOTH FINISH THESE HOLES TO BOARD SURFACE FROM THE TOP SIDE AFTER CONDUCTIVE FILLING.
- * HEIGHT OF THE COPPER PADS IN THESE AREA NEED TO BE EVEN WITHIN 1.5 MIL.

NOTES (UNLESS OTHERWISE SPECIFIED):

1. BOARD THICKNESS : 62 +/- 4 MILS
2. DIELECTRIC : REFER STACK UP.
3. NUMBER OF LAYERS: 8
4. SOLDERMASK : LPI GREEN.
5. SILKSCREEN : WHITE EPOXY INK.
6. NO VENDOR LOGO OR NAME ON THE BOARD.
7. REMOVE THE NON-FUNCTIONAL PADS ON ALL INNER LAYERS.
8. PLATING : IMMERSION GOLD.
9. MAXIMUM WARP AND TWIST SHALL NOT EXCEED .005 PER INCH.
10. ANY CHANGES MADE BY THE PCB FABRICATOR TO THE FILM OR THE GERBER FILES MUST BE APPROVED BY PACTRON.
11. DEBURR ALL SHARP EDGES.
12. BOARD DIMENSIONS ARE IN INCHES.
13. 18 MIL TRACES REQUIRES 50 OHM +/-5% SINGLE ENDED IMPEDANCE ON TOP AND BOTTOM LAYER.
14. 4.75 MIL TRACES REQUIRES 50 OHM +/-5% SINGLE ENDED IMPEDANCE ON INNER LAYER.
15. 13.75\15.75\13.75 MIL REQUIRED 100 OHM +/-5% DIFFERENTIAL IMPEDANCE ON TOP,BOTTOM LAYER.
16. THIS BOARD SHOULD BE LEAD FREE.

| | | | |
|---|---------|--------|---------------|
| COMPANY: TEXAS INSTRUMENTS | | | |
| TITLE: DS100DF410EVK,DS110DF410EVM,DS125DF410EVM | | | |
| SIZE | FSCM NO | DWG NO | SV600673B.brd |
| SCALE | | | SHEET |